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3/4/03  
Patent Application

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Applicant:** Gerald Friese

**Examiner:** Powell, William A.

**Serial No:** 09/893,160

**Group:** Art Unit 1765

**Filed:** June 27, 2001

**Docket:** 8055-83CIP (In1292USD1)

**For:** **POWER PADS FOR APPLICATION OF HIGH CURRENT  
PER BOND PAD IN SILICON TECHNOLOGY**

Assistant Commissioner for Patents  
Washington, D.C. 20231

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**AMENDMENT**

This is a response to the Office Action mailed on December 04, 2002. Please amend the above-identified application as follows:

**IN THE SPECIFICATION:**

Please insert the following paragraph after the Title on page 1 of Applicant's specification:


**Cross-Reference to Related Application**

B1  
This application is a Continuation-in-Part of U.S. Patent Application Serial No. 09/543,691, filed on April 5, 2000.

**CERTIFICATE OF MAILING 37 C.F.R. § 1.8(a)**

I hereby certify that this correspondence (and any document referred to as being attached or enclosed) is being deposited with the United States Postal Service as first class mail, postage paid in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on March 4, 2003.

Dated: 3/4/03

  
Frank V. DeRosa